	REVISIONS		
LTR	DESCRIPTION	DATE	APPROVED
A	Update the Title; update the test conditions in Table I. Add Thermal resistance in section 1.4. Add Interface Schematic Figures: 3, 4, 5, and 6 PHN	17-04-18	Thomas M. Hess



Prepared in accordance with ASME Y14.24

REV

Vendor item drawing

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1	16-05-04 APPROVED BY CHARLES F. SAFFLE					- MICROCIRCUIT, LINEAR, 0.2 GHz TO 8 GHz, GaAs, HBT MMIC, DIVIDE BY 8 PRESCALER																
SIZE CODE IDENT. NO. A 16236		DWG NO. V62/16609																				
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AMSC N/A 5962-V040-17

1. SCOPE

- 1.1 <u>Scope</u>. This drawing documents the general requirements of a high performance 0.2 GHz to 8 GHz, GaAs, HBT MMIC, Divide by 8 Prescaler microcircuit, with an operating temperature range of -55°C to +105°C.
- 1.2 <u>Vendor Item Drawing Administrative Control Number</u>. The manufacturer's PIN is the item of identification. The vendor item drawing establishes an administrative control number for identifying the item on the engineering documentation:

V62/16609	-	<u>01</u>	<u>X</u>	<u>E</u>
		<u></u> _		
Drawing		Device type	Case outline	Lead finish
number		(See 1.2.1)	(See 1.2.2)	(See 1.2.3)

1.2.1 Device type(s).

 Device type
 Generic
 Circuit function

 01
 HMC434
 0.2 GHz to 8 GHz, GaAs, HBT MMIC, Divide by 8 Prescaler

1.2.2 <u>Case outline(s)</u>. The case outline(s) are as specified herein.

Outline letter	Number of pins	JEDEC PUB 95	Package style
X	6	MO-178-AB	Plastic small outline package

1.2.3 <u>Lead finishes</u>. The lead finishes are as specified below or other lead finishes as provided by the device manufacturer:

Finish designator	<u>Material</u>
Α	Hot solder dip
В	Tin-lead plate
С	Gold plate
D	Palladium
E	Gold flash palladium
Z	Other

1.3 Absolute maximum ratings. 1/

Supply voltage (VCC)	
Temperature:	
Operating	-55°C to +105°C
Storage	-65°C to +125°C
Junction, T _J	135°C
Nominal (T _A = 105°C)	119°C
Reflow	260°C
Electrostatic discharge sensitivity: Human body model (HBM)	Class 0

^{1/} Stresses beyond those listed under "absolute maximum rating" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

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1.4 Thermal Resistance.

Package Type	θ _{JA} <u>2</u> /	θ _{JC} <u>3</u> /	Unit
Case Outline X	359	70	°C/W

2. APPLICABLE DOCUMENTS

JEDEC Solid State Technology Association

JEDEC PUB 95 - Registered and Standard Outlines for Semiconductor Devices

JESD51-12 - Guidelines for Reporting and Using Electronic Package Thermal Information.

(Copies of these documents are available online at http://www.jedec.org or from JEDEC – Solid State Technology Association, 3103 North 10th Street, Suite 240–S, Arlington, VA 22201-2107).

3. REQUIREMENTS

- 3.1 <u>Marking</u>. Parts shall be permanently and legibly marked with the manufacturer's part number as shown in 6.3 herein and as follows:
 - A. Manufacturer's name, CAGE code, or logo
 - B. Pin 1 identifier
 - C. ESDS identification (optional)
- 3.2 <u>Unit container</u>. The unit container shall be marked with the manufacturer's part number and with items A and C (if applicable) above.
- 3.3 <u>Electrical characteristics</u>. The maximum and recommended operating conditions and electrical performance characteristics are as specified in 1.3, 1.4, and table I herein.
 - 3.4 Design, construction, and physical dimension. The design, construction, and physical dimensions are as specified herein.
 - 3.5 Diagrams.
 - 3.5.1 Case outline. The case outline shall be as shown in 1.2.2 and figure 1.
 - 3.5.2 <u>Terminal connections</u>. The terminal connections shall be as shown in figure 2.
 - 3.5.3 GND Interface Schematic. The GND interface Schematic shall be as shown in figure 3.
 - 3.5.4 IN Interface Schematic. The IN interface Schematic shall be as shown in figure 4.
 - 3.5.5 OUT Interface Schematic. The OUT interface Schematic shall be as shown in figure 5.
 - 3.5.6 VCC Interface Schematic. The VCC interface Schematic shall be as shown in figure 6.

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^{2/} Simulated values per JEDEC JESD51-12 standards.

^{3/} Junction to GND package pin.

TABLE I. Electrical performance characteristics. 1/

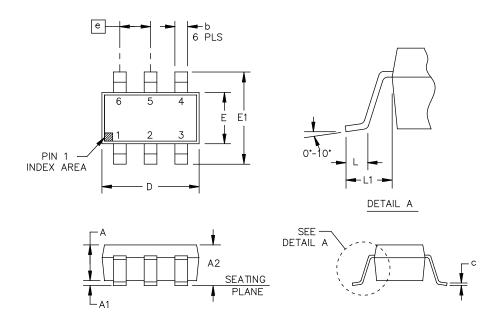
Test Symbol		Conditions <u>2</u> /		Unit		
		unless otherwise specified	Min	Тур	Max	
Radio Frequency (RF) I	nput					
Frequency 3/		Sine wave input	0.2		8	GHz
Power		f _{IN} = 1.0 GHz to 3.0 GHz	-10		+10	dBm
1 OWO!		f _{IN} = 3.0 GHz to 8.0 GHz	0		10	dBm
RF Output						
SSB Phase noise		100 kHz offset, PIN = 0 dBm, fIN = 4.0 GHz		-150		dBc/Hz
Power		f _{IN} = 1.0 GHz to 8.0 GHz	-5	-2		dBm
Reverse Leakage						
Reverse Leakage		PIN = 0 dBm, fIN = 4.0 GHz , output terminated		-25		dBm
Supply	•					
Voltage	Vcc		2.85	3	3.15	V
Current	Icc			62	83	mA

^{1/} Testing and other quality control techniques are used to the extent deemed necessary to assure product performance over the specified temperature range. Product may not necessarily be tested across the full temperature range and all parameters may not necessarily be tested. In the absence of specific parametric testing, product performance is assured by characterization and/or design.

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 $^{2/}V_{CC} = 3 \text{ V}$, $T_A = 25^{\circ}\text{C}$, 50 Ω system, unless otherwise noted. PIN is input power.

^{3/} Below 200 MHz, a square wave input is required.



Symbol	Inches Millimete				Millimeter	S	
	Minimum	Medium	Maximum	Minimum	Medium	Maximum	
Α	.035	.045	.051	0.90	1.15	1.30	
A1	.0019		.005	0.05		0.15	
A2	.037		.057	0.95		1.45	
b	.011		.019	0.30		0.50	
С	.003		.007	0.08		0.20	
D	.110	.114	.118	2.80	2.90	3.00	
Е	.059	.062	.066	1.50	1.60	1.70	
E1	.102	.110	.118	2.60	2.80	3.00	
е	.037 BSC				0.95 BSC	;	
L	.013	.017	.021	0.35	0.45	0.55	
L1		.023 BSC		0.60 BSC			

NOTES:

- Controlling dimensions are millimeter, inch dimensions are given for reference only.
 Falls with JEDEC MO-178-AB.

FIGURE 1. Case outline.

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Device type		01	
Case outline		X	
Terminal number	Terminal symbol	Description	
1, 4	NIC	Not Internally Connected. These pins can be connected to RF and dc ground without affecting performance. The NIC pins are typically tied to GND for enhanced thermal performance (but not required).	
2	GND	Ground. This pin must be connected to both RF and dc ground.	
3	IN	RF Input. This pin must be dc blocked.	
5	Vcc	Supply Voltage (3 V).	
6	OUT	RF Output. This pin must be dc blocked.	

FIGURE 2. <u>Terminal connections</u>.



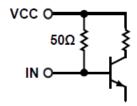


FIGURE 3. GND Interface Schematic.

FIGURE 4. IN Interface Schematic.

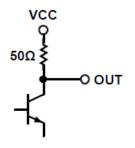




FIGURE 5. OUT Interface Schematic.

FIGURE 6. Vcc Interface Schematic.

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4. VERIFICATION

4.1 <u>Product assurance requirements</u>. The manufacturer is responsible for performing all inspection and test requirements as indicated in their internal documentation. Such procedures should include proper handling of electrostatic sensitive devices, classification, packaging, and labeling of moisture sensitive devices, as applicable.

5. PREPARATION FOR DELIVERY

- 5.1 <u>Packaging</u>. Preservation, packaging, labeling, and marking shall be in accordance with the manufacturer's standard commercial practices for electrostatic discharge sensitive devices.
 - 6. NOTES
 - 6.1 ESDS. Devices are electrostatic discharge sensitive and are classified as ESDS class 0.
- 6.2 <u>Configuration control</u>. The data contained herein is based on the salient characteristics of the device manufacturer's data book. The device manufacturer reserves the right to make changes without notice. This drawing will be modified as changes are provided.
- 6.3 <u>Suggested source(s) of supply</u>. Identification of the suggested source(s) of supply herein is not to be construed as a guarantee of present or continued availability as a source of supply for the item. DLA Land and Maritime maintains an online database of all current sources of supply at https://landandmaritimeapps.dla.mil/programs/smcr/default.aspx

Vendor item drawing administrative control number 1/	Device manufacturer CAGE code	Ordering Quantity	Vendor part number
V62/16609-01XE	24355	Small Reel units = 50	HMC434SRJZ-EP-PT
		Reel units= 500	HMC434SRJZ-EP-R7

1/ The vendor item drawing establishes an administrative control number for identifying the item on the engineering documentation.

<u>CAGE code</u> <u>Source of supply</u>

24355 Analog Devices
Route 1 Industrial Park

P.O. Box 9106 Norwood, MA 02062

Point of contact: Raheen Business Park Limerick, Ireland

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